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(54) Title: DEPOSITION RATE ENHANCEMENT OF AMORPHOUS CARBON HARD MASK FILM BY PURELY CHEMICAL MEANS

(57) Abstract: Provided herein are methods and related apparatus for depositing an ashable hard mask (AHM) on a substrate at high temperatures using an additive that reduces a competing etch process. Sulfur hexafluoride may be used to improve the deposition rate of the AHM with minimal changes to the properties of the resulting film.

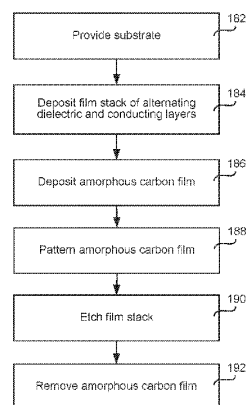


FIG. 1

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